

MA27P060G

Silicon planar type

For high frequency switch

■ Features

- Low terminal capacitance: $C_t \leq 0.6$ pF
- Low forward dynamic resistance: $r_f \leq 1.2$ Ω

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	60	V
Forward current	I_F	100	mA
Power dissipation *	P_D	150	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: With a glass epoxy PC board.

■ Package

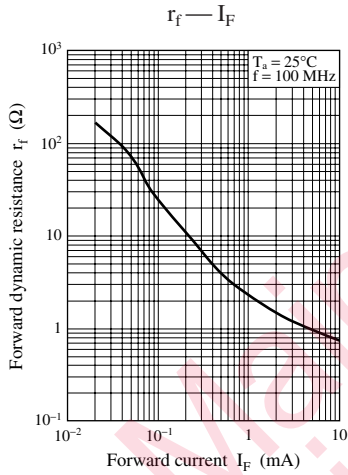
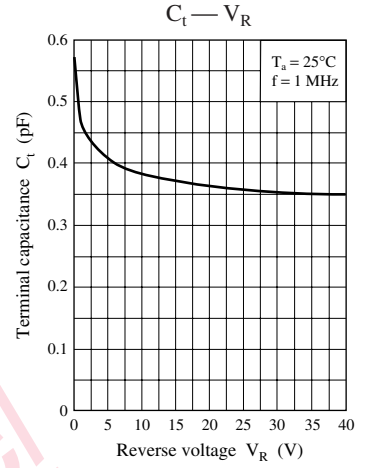
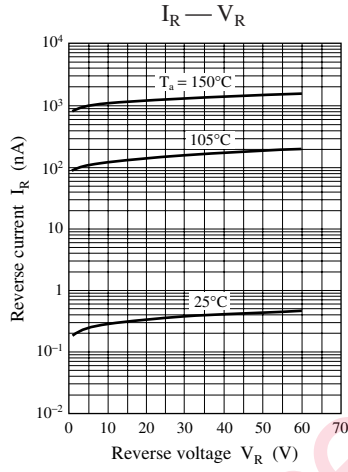
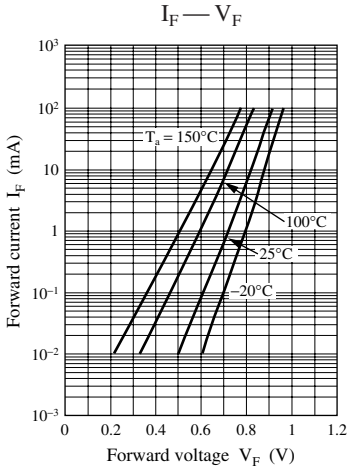
- Code
SSSMINI2-F3
- Pin Name
1: Anode
2: Cathode

■ Marking Symbol: M

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10$ mA		0.85	1.0	V
Reverse current	I_R	$V_R = 60$ V		1.0	100	nA
Terminal capacitance	C_t	$V_R = 1$ V, $f = 1$ MHz		0.45	0.6	pF
Forward dynamic resistance	r_f	$I_F = 10$ mA, $f = 100$ MHz		0.80	1.2	Ω

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

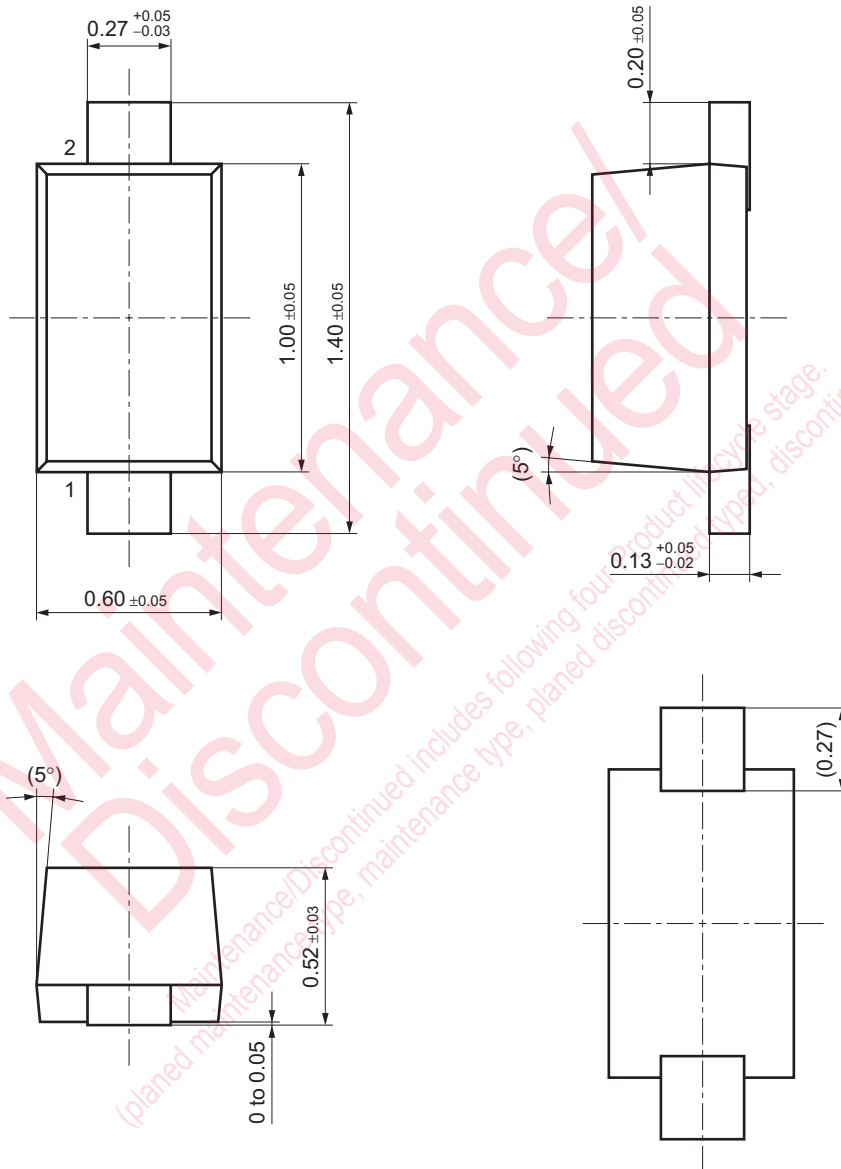


Maintenance/Discontinued
 (planned maintenance type, maintenance type, planned discontinued type, discontinued type)

Maintenance/Discontinued includes following four Product lifecycle stage.

SSSMini2-F3

Unit: mm



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